



Materials Declaration

Package	MQFP
Body Size	28 X 28
LeadCount	208
Option	Pb-Free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
SiO2 Filler	87.00	4.16 E+00	718662
Epoxy resin	7.50	3.59 E-01	61954
Phenol Resin	5.50	2.63 E-01	45433

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	95.90	7.88 E-01	136134
Ni	3.20	2.63 E-02	4543
Si	0.73	5.96 E-03	1029
Mg	0.18	1.44 E-03	248

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100.0	5.98 E-03	1032

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100.0	3.18 E-02	5494

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	6.07 E-02	10488

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100.0	7.81 E-02	13485

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag Filler	76.0	6.59 E-03	1139
Diester resin	10.5	9.11 E-04	157
Functionalized urethane	8.0	6.94 E-04	120
Epoxy resin	5.5	4.77 E-04	82

Molding Compound		
Item	PPM	Method
Pb	None Detected	US EPA 3052, ICP -OES
Cd	None Detected	US EPA 3052, ICP -OES
Hg	None Detected	US EPA 3052, ICP -OES
Cr+6	None Detected	US EPA 3060A & 7196A, UV-VIS
PBB	None Detected	Analysis performed by GC/MS
PBDE	None Detected	Analysis performed by GC/MS

Die Attach Paste		
Item	PPM	Method
Pb	None Detected	US EPA 3052, ICP
Cd	None Detected	US EPA 3052, ICP
Hg	None Detected	US EPA 3052, ICP
Cr+6	None Detected	US EPA 3060A, UV-VIS
PBB	None Detected	US EPA 3546, Analysis performed by GC/MS
PBDE	None Detected	US EPA 3546, Analysis performed by GC/MS

Package Totals	
Weight (g)	PPM
5.79 E+00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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Package	MQFP
Body Size	28 X 28
LeadCount	208
Option	SnPb

Molding Compound			
Item	% of Compound	Weight (g)	PPM
SiO2 Filler	87.00	4.16 E+00	718662
Epoxy resin	7.50	3.59 E-01	61954
Phenol Resin	5.50	2.63 E-01	45433

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	95.90	7.88 E-01	136134
Ni	3.20	2.63 E-02	4543
Si	0.73	5.96 E-03	1029
Mg	0.18	1.44 E-03	248

Internal Leadframe Plating			
	% of Plating	Weight (g)	PPM
Ag	100	5.98 E-03	1032

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	85	2.70 E-02	4670
Pb	15	4.77 E-03	824

Bond Wires			
	% of Wire	Weight (g)	PPM
Au	99.99	6.07 E-02	10488

Chip			
	% of Chip	Weight (g)	PPM
Si	100	7.81 E-02	13485

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag Filler	76.0	6.59 E-03	1139
Resin	24.0	2.08 E-03	360

Package Totals

Weight (g)	PPM
5.79 E+00	1000000

Molding Compound		
Item	PPM	Method
Pb	None Detected	US EPA 3052, ICP-OES
Cd	None Detected	US EPA 3052, ICP-OES
Hg	None Detected	US EPA 3052, ICP-OES
Cr+6	None Detected	US EPA 3060A & 7196A, UV-VIS
PBB	None Detected	Analysis was performed by GC/MS
PBDE	None Detected	Analysis was performed by GC/MS

Die Attach Paste		
Item	PPM	Method
Pb	3	US EPA 3052, ICP-OES
Cd	None Detected	US EPA 3052, ICP-OES
Hg	None Detected	US EPA 3052, ICP-OES
Cr+6	None Detected	US EPA 3060A & 7196A, UV-VIS
PBB	None Detected	Analysis was performed by GC/MS
PBDE	None Detected	Analysis was performed by GC/MS

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